METHODS FOR ENHANCING DIE SAW AND PACKAGING RELIABILITY

ABSTRACT

[0020] A wafer device is disclosed for improving reliability of circuits fabricated in an active area on a silicon substrate. A seal ring is fabricated around the active area, and a shallow trench isolation is also formed between the seal ring and a scribe line by etching into a portion of the silicon substrate, wherein the seal ring and the shallow trench isolation prevent die saw induced crack from propagating to the active area when the active area is cut along the scribe line.

(FIG. 1A)